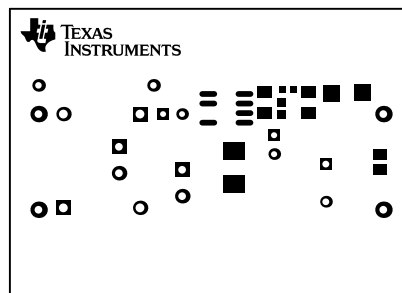
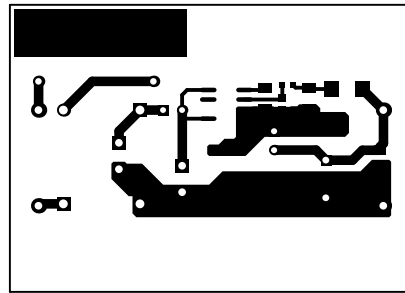


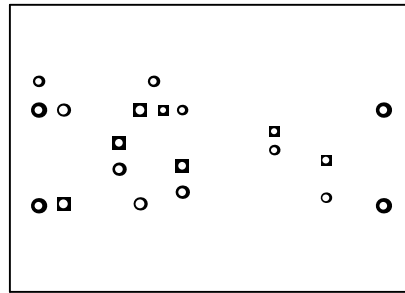
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 8/5/2013	9:04:15 AM	TEXAS INSTRUMENTS



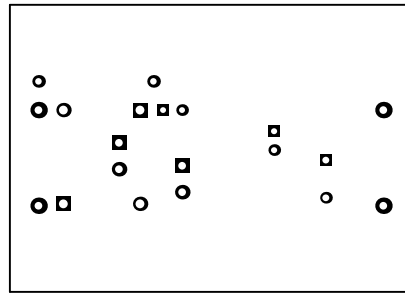
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 8/5/2013 9:04:16 AM	TEXAS INSTRUMENTS	



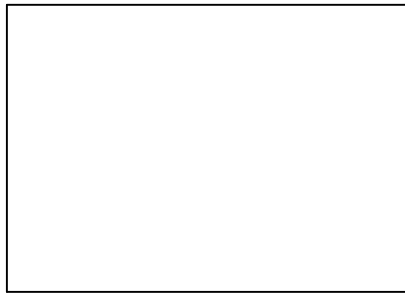
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 8/5/2013 9:04:16 AM	TEXAS INSTRUMENTS	



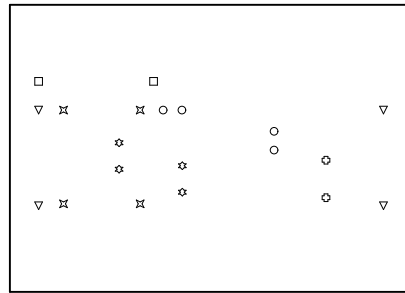
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 8/5/2013 9:04:16 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 8/5/2013 9:04:17 AM	TEXAS INSTRUMENTS	



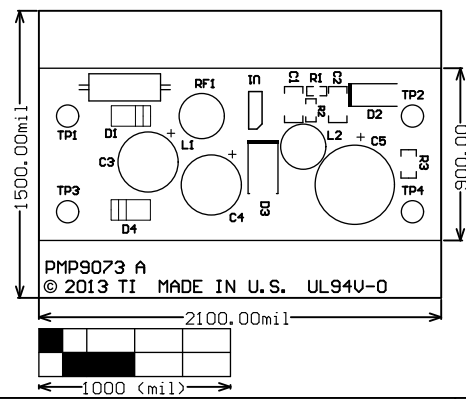
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 8/5/2013 9:04:17 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	4	31mil (0.787mm)	PTH	Round
□	2	33.465mil (0.85mm)	PTH	Round
⊕	2	35mil (0.889mm)	PTH	Round
☆	4	39.37mil (1mm)	PTH	Round
▽	4	40mil (1.016mm)	PTH	Round
⊗	4	45.276mil (1.15mm)	PTH	Round
20 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 8/5/2013	9:04:18 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M@pB@e@l@B@y@n@s@i@o@s			
PLOT NAME = Board Dimensions	GENERATED : 8/5/2013 9:04:18 AM	TEXAS INSTRUMENTS	

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